## IN THE ABSTRACT

Page 137, line 4, change "leak" to --leakage--.

## IN THE CLAIMS

Please cancel claims 1-9 without prejudice.

Please add new claims 14-15 as follows:

- --14. A method of manufacturing a semiconductor device in which there are first and second types of transistors formed on a single semiconductor substrate, comprising the steps of:
- (a) selectively forming a field oxide film on a main surface of said semiconductor substrate to thereby define first and second regions in which said first and said second types of transistors are formed;
  - (b) forming an oxide film on said first and said second regions; and
- (c) forming a control electrode of a polysilicon layer on said first and said second regions,

wherein said step (c) includes the steps of:

- (c-1) introducing an impurity of the same conductivity as a source/drain layer into said polysilicon layer within said first active region at a relatively low dose n1; and
- (c-2) introducing said impurity into said polysilicon layer within said second active region at a relatively high dose n2 while introducing nitrogen into a lower portion of said polysilicon layer within said second active region at a dose n3.
- 15. The method of manufacturing a semiconductor device of claim  $\sqrt{3}$ , wherein said dose n1 is 5 x  $10^{14}$ /cm<sup>2</sup>, said dose n2 is 5 x  $10^{15}$ /cm<sup>2</sup>, and said dose n3 is 1 x  $10^{15}$ /cm<sup>2</sup>.--